



**THE DATASHEET OF
ZXMN6A09KTC**



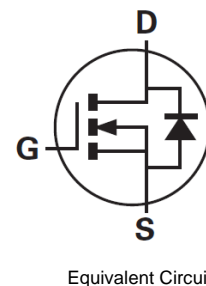
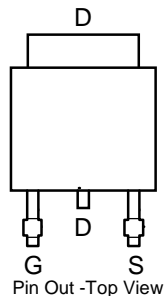
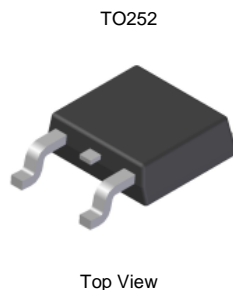
Product Summary

BV _{DSS}	Max R _{DS(on)}	Max I _D T _A = +25°C (Note 4)
60V	40mΩ @ V _{GS} = 10V	7.7A
	60mΩ @ V _{GS} = 4.5V	6.3A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- DC-DC Converters
- Power Management Functions
- Disconnect Switches
- Motor Control



Features and Benefits

- Low On-Resistance
- Fast Switching Speed
- Low Gate Drive
- **Lead-Free Finish; RoHS Compliant (Note 1)**
- **Halogen and Antimony Free. "Green" Device (Note 2 & 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

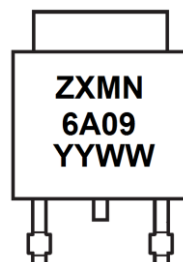
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish. Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.33 grams (Approximate)

Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMN6A09KTC	ZXMN6A09	13	16	2,500

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



ZXMN6A09 = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 10 = 2010)
 WW = Week (01 - 53)

Maximum Ratings (@T_A = +25°C unless otherwise specified.)

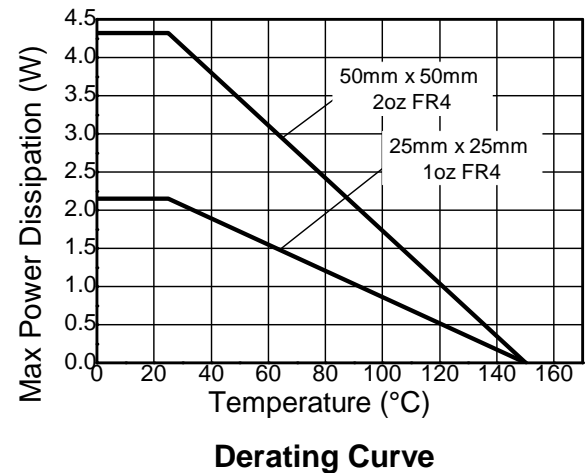
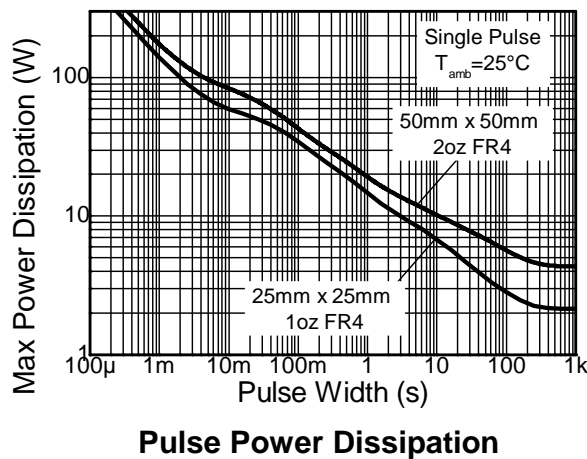
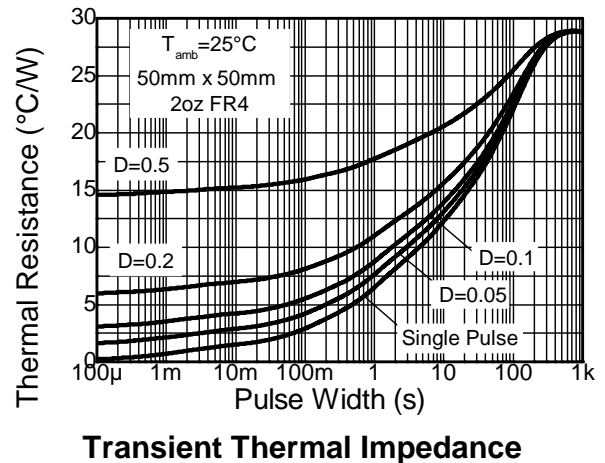
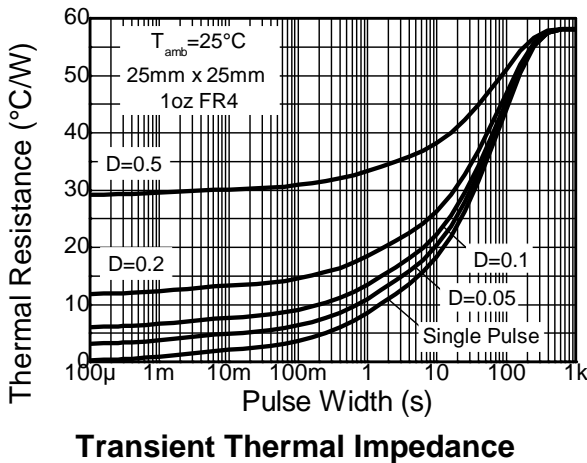
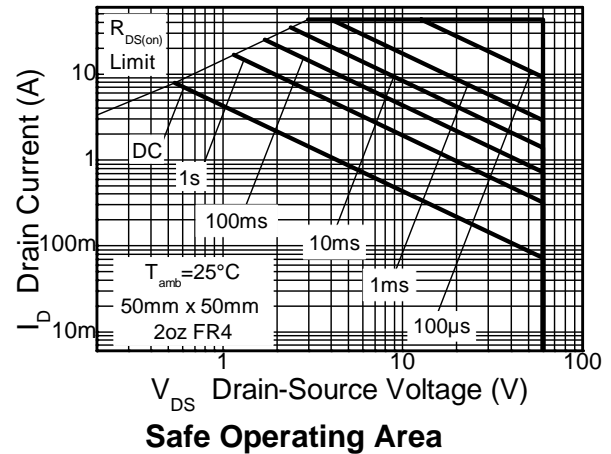
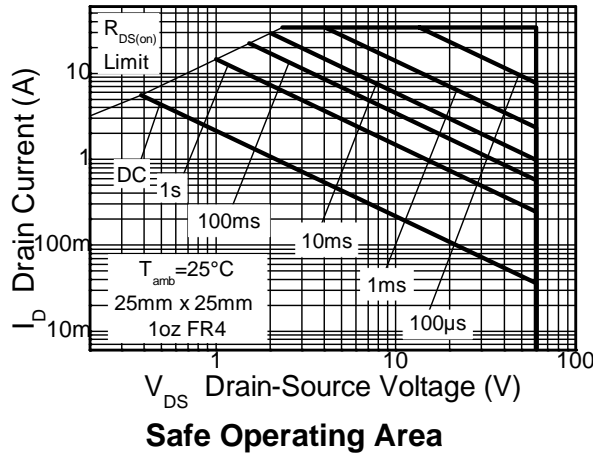
Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	60	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current	V _{GS} = 10V	(Note 6)	11.8	A
		T _A = +70°C (Note 6)	9.6	
		(Note 5)	7.7	
Pulsed Drain Current		I _{DM}	43	A
Continuous Source Current (Body Diode)		I _S	10.8	A
Pulsed Source Current (Body Diode)		I _{SM}	43	A

Thermal Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 5)	P _D	4.3	W mW/°C
			34.4	
	(Note 6)		10.1	
			80.8	
	(Note 8)		2.15	
Thermal Resistance, Junction to Ambient	(Note 5)	R _{θJA}	29	°C/W
	(Note 6)		12.3	
	(Note 8)		58.1	
Thermal Resistance, Junction to Lead	(Note 9)	R _{θJL}	1.04	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C

- Notes:
- For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 - For a device surface mounted on FR4 PCB measured at t ≤ 10 sec.
 - Repetitive rating 50mm x 50mm x 1.6mm FR4 PCB, D = 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.
 - For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 - Thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics

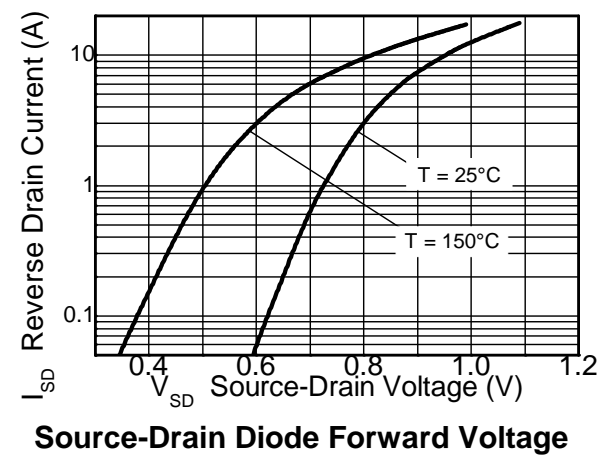
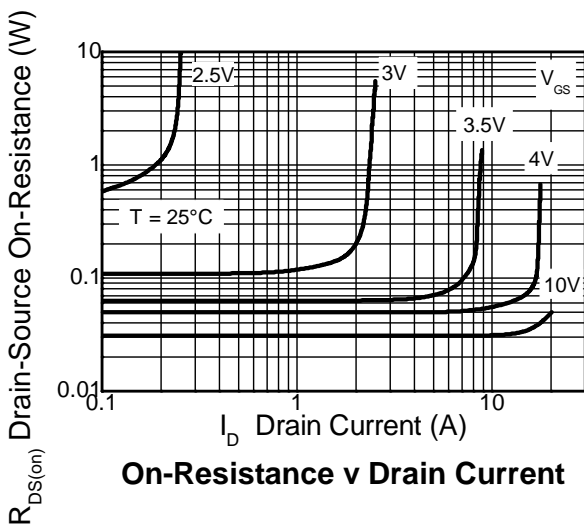
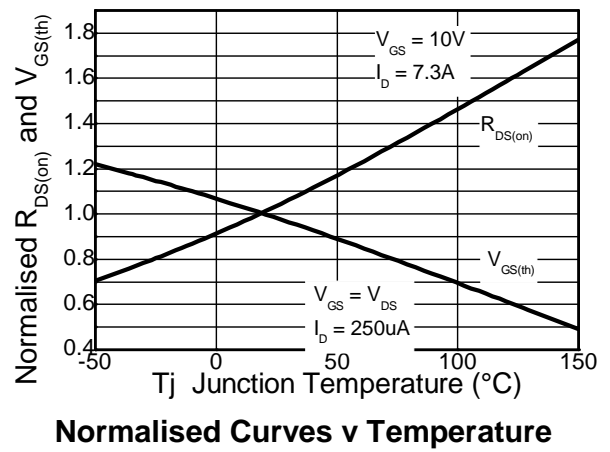
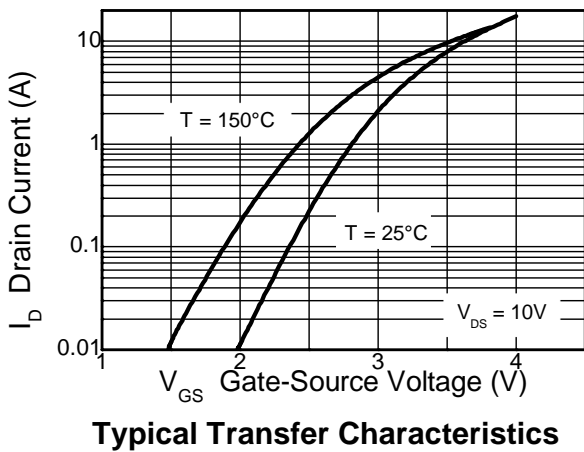
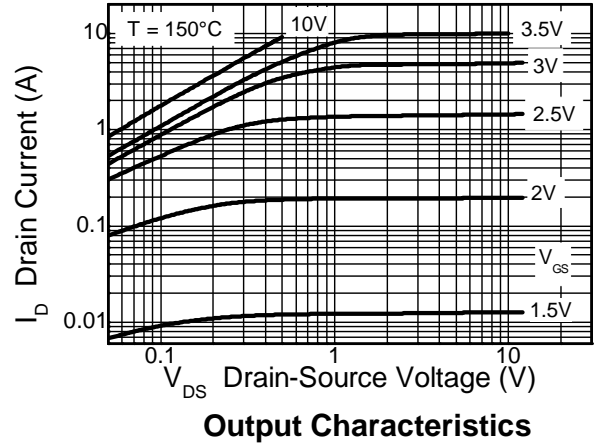
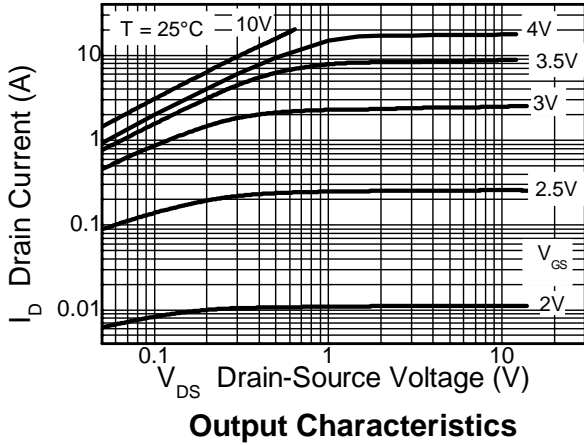


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

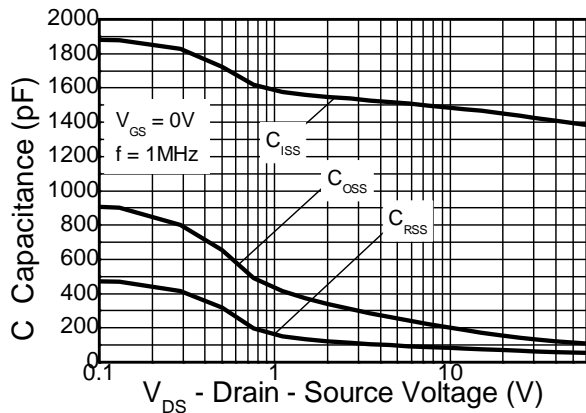
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	60	—	—	V	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 60\text{V}$, $V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(th)}$	1.0	—	3.0	V	$I_D = 250\mu\text{A}$, $V_{DS} = V_{GS}$
Static Drain-Source On-Resistance (Note 10)	$R_{DS(on)}$	—	—	40	m Ω	$V_{GS} = 10\text{V}$, $I_D = 7.3\text{A}$
				60		$V_{GS} = 4.5\text{V}$, $I_D = 5.6\text{A}$
Forward Transconductance (Notes 10 & 11)	g_{fs}	—	15	—	S	$V_{DS} = 15\text{V}$, $I_D = 7.3\text{A}$
Diode Forward Voltage (Note 10)	V_{SD}	—	0.85	0.95	V	$I_S = 6.6\text{A}$, $V_{GS} = 0\text{V}$, $T_J = +25^\circ\text{C}$
Reverse Recovery Time (Note 11)	t_{rr}	—	25.6	—	ns	$I_S = 3\text{A}$, $di/dt = 100\text{A}/\mu\text{s}$
Reverse Recovery Charge (Note 11)	Q_{rr}	—	26.0	—	nC	$T_J = +25^\circ\text{C}$
DYNAMIC CHARACTERISTICS (Note 11)						
Input Capacitance	C_{iss}	—	1426	—	pF	$V_{DS} = 30\text{V}$, $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$
Output Capacitance	C_{oss}	—	134	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	64	—	pF	
Total Gate Charge (Note 12)	Q_g	—	15	—	nC	$V_{GS} = 4.5\text{V}$, $V_{DS} = 30\text{V}$, $I_D = 5.6\text{A}$
Total Gate Charge (Note 12)	Q_g	—	29	—	nC	$V_{GS} = 10\text{V}$, $V_{DS} = 30\text{V}$ $I_D = 7.3\text{A}$
Gate-Source Charge (Note 12)	Q_{gs}	—	7.0	—	nC	
Gate-Drain Charge (Note 12)	Q_{gd}	—	4.7	—	nC	
Turn-On Delay Time (Note 12)	$t_{D(on)}$	—	4.8	—	ns	
Turn-On Rise Time (Note 12)	t_r	—	4.6	—	ns	$V_{DD} = 30\text{V}$, $V_{GS} = 10\text{V}$ $I_D = 1\text{A}$, $R_G \cong 6.0\Omega$
Turn-Off Delay Time (Note 12)	$t_{D(off)}$	—	32.5	—	ns	
Turn-Off Fall Time (Note 12)	t_f	—	14.5	—	ns	

- Notes:
10. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
 11. For design aid only, not subject to production testing.
 12. Switching characteristics are independent of operating junction temperatures.

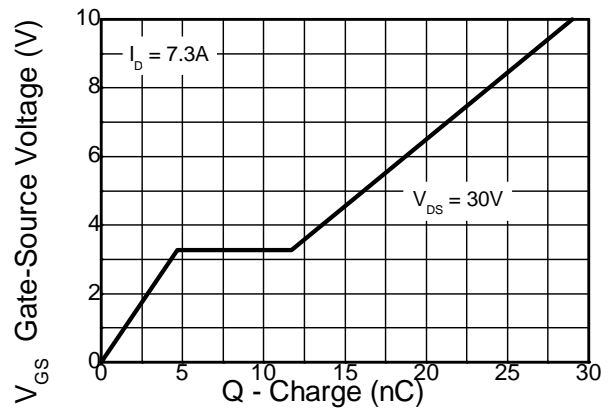
Typical Characteristics



Typical Characteristics (cont.)

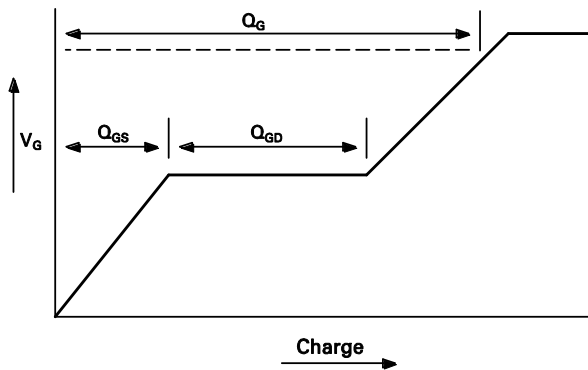


Capacitance v Drain-Source Voltage

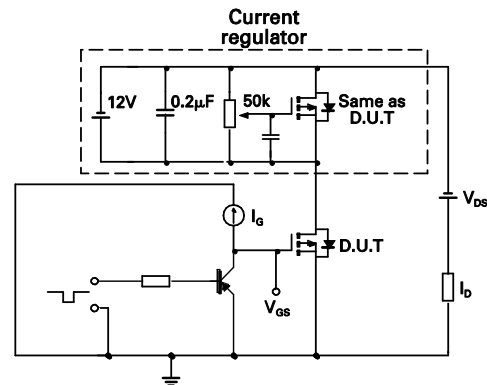


Gate-Source Voltage v Gate Charge

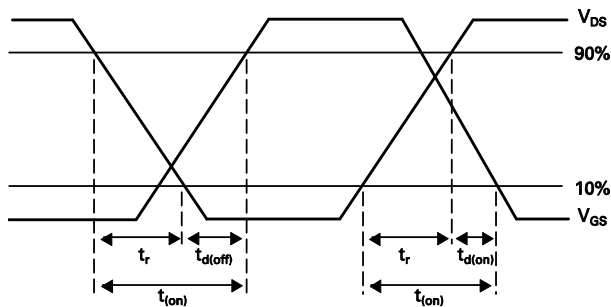
Test Circuits



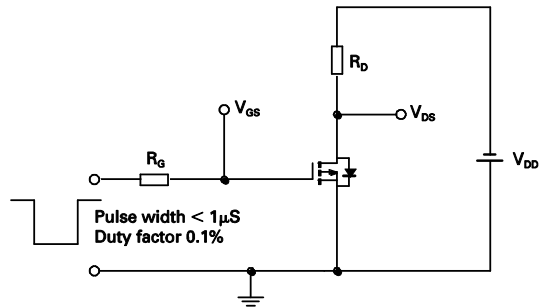
Basic gate charge waveform



Gate charge test circuit



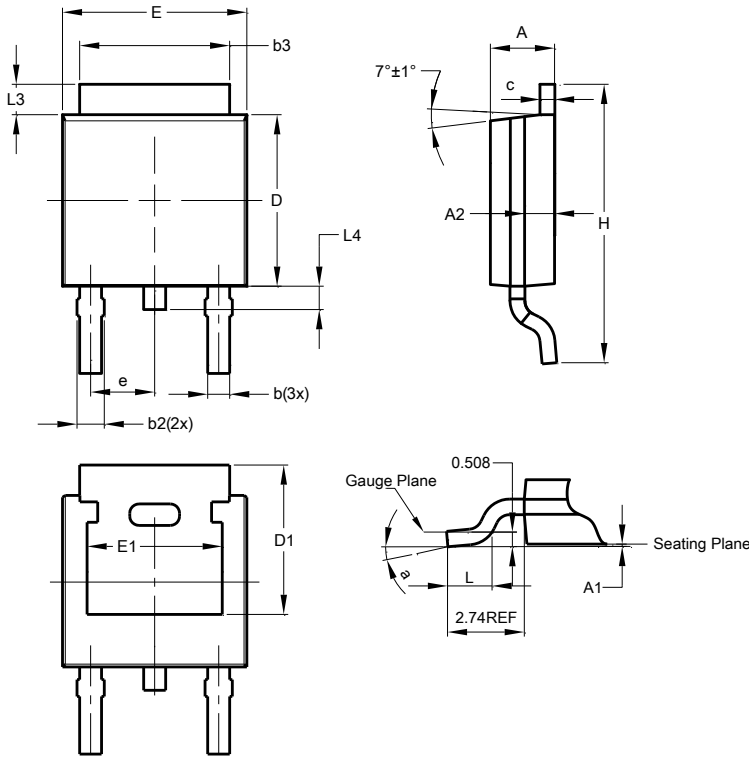
Switching time waveforms



Switching time test circuit

Package Outline Dimensions

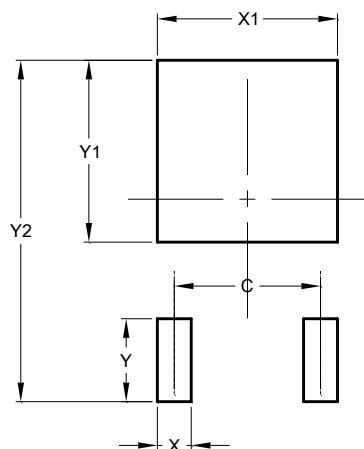
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

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